



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

**David R. Hembree**

**Serial No.: 09/834,297**

**Filed: April 12, 2001**

**For: CHIP ON BOARD WITH HEAT SINK  
ATTACHMENT**

**Confirmation No.: 6489**

**Examiner: J. Mitchell**

**Group Art Unit: 2827**

**Attorney Docket No.: 2269-3592.SUS  
(97-0321.05/US)**

**Notice of Allowance Mailed:**

**September 23, 2003**

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

December 22, 2003  
Date

Signature

Deidra J. Pfeil  
Name (Type/Print)

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Title** appear on page 3 of this paper.

**Amendments to the Specification** appear on page 4 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper.

**Amendments to the Drawings** appear on page 7 of this paper and include both attached replacement sheets and annotated sheets showing changes.

**Remarks** begin on page 8 of this paper.

An **Appendix A** including a clean version of the amended substitute specification is attached following page 8 of this paper.

An **Appendix B** including a marked-up version of the amended substitute specification showing changes made is attached following Appendix A of this paper.

An **Appendix A** including amended drawing figures is attached following Appendix B of this paper.

**IN THE TITLE:**

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**CHIP ON BOARD WITH HEAT SINK ATTACHMENT AND ASSEMBLY**